

D1  
correl.

Referring to these figures, the connection structure includes TCPs 4ap and 8p loaded with driver ICs (as drive semiconductor circuits) 5p and 9p and copper foil patterns 32 (as output electrodes), glass substrates 1ap and 1bp for a liquid crystal panel 1 having electrode terminals 12p extended to peripheries thereof, and ACFs (anisotropic conductive films or anisotropic conductive adhesive) 31 for heat-bonding the copper foil patterns 32 on the TCPs with the electrode terminals 12p on the glass substrates. Further, PCB boards 3p for supplying a power and control signals to the driver ICs 5p and 9p are connected with copper foil patterns 17 (as input electrodes) of the TCPs 4ap with solder 20p.--

Please replace the paragraph beginning at page 8, line 14 with the following replacement paragraph:

D2

--Figure 2 is a partial sectional view taken along a line 2-2 in Figure 1.--

Please replace the paragraphs beginning at page 9, line 9, and page 9, line 16, respectively, with the following paragraphs:

D3

--Figure 13 is a partial sectional view taken along a line 13-13 in Figure 12.--

D4

--Figure 1 is a plan view of a liquid crystal display apparatus, as an embodiment of display apparatus, including a drive circuit connection structure according to a first embodiment of the present invention, and Figure 2 is a sectional view taken along a line 2-2